Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	2	composite with (case shell enclosure cover) with "circuit board" with connector	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 13:18
S1	1	10/705906	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 13:15
S2	1	"circuit card" and "connector" and "thermal filler" and "lightweight"	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/12 14:43
S3	1	"circuit card" and "connector" and "thermal filler"	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/12 14:43
S4	189	"circuit card" and "connector" and filler	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/12 14:44
S5	343	(361/705).CCLS.	US-PGPUB; USPAT; USOCR	OR .	OFF	2005/10/12 14:45
S6	1	S4 and S5	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/12 14:44
S13	14	"circuit card" with (pot\$3 or encapsulat\$3 or environment\$3) with thermal	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/14 10:14
S14	1006	"chip" with (pot\$3 or encapsulat\$3 or environment\$3) with thermal	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/14 10:18
S15	344	(361/705).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/14 15:51
S16	8	S15 and S14	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/14 10:15
S17	31494	(pot\$3 or encapsulat\$3 or environment\$3) with thermal	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/14 10:18
S18	46	S15 and S17	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/14 10:18
S19	1	("4764845").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/14 15:46
S20	11	("4764845").URPN.	USPAT	OR	ON	2005/10/14 15:49
S21	8440	expand\$4 near3 foam	USPAT	OR	ON	2005/10/14 15:50

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S24	193548	"361".clas. or "165".clas.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/14 15:52
S25	97	S21 and S24	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/14 16:19
S26	11	S25 and holes with (shell or housing or case)	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/14 16:20
S27	18174	(pot\$3 or encapsulat\$4 or filler) with thermal	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 07:43
S28	118038	"361".clas.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 07:43
S29	872	S27 and S28	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 07:47
S30	1022018	(inject\$3 or foam\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 07:47
S31	247	S29 and S30	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 07:57
S32	755	(mechanical or environment\$2) near5 filler with (pot\$3 or encapsulat\$3 or environment\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 07:59
S33	9	S28 and S32	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 08:01
S34	6113	("expandable foam" or foam near3 place)	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 08:03
S35	2	S31 and S34	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 08:03
S36	344	(361/705).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/17 08:03
S37	1	S36 and S34	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 08:04

S38	17	(("6317324") or ("5812375") or ("5887435") or ("6101090") or ("6101094") or ("6175501") or ("6452804") or ("5777847") or ("5768104") or ("4409641") or ("4546412") or ("5508885") or ("5646831") or ("4849858") or ("5672414") or ("5208732") or ("5541448")).PN. or (2002/0158330).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/17 09:00
S39	1	"20020158330"	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 09:08
S40	155	("curcuit card" or substrate) with ("expandable foam" or foam near3 place)	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 09:10
S41	158	("circuit card" or substrate) with ("expandable foam" or foam near3 place)	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 09:13
S42	1	S28 and S41	US-PGPUB; USPAT; USOCR	OR .	ON	2005/10/17 09:11
S43	3	("circuit card") with ("expandable foam" or foam near3 place)	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 09:22
S44	16	"Circuit card" with (opening or via or hole) with inject\$3	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 09:36
S45	0	("6706972").URPN.	USPAT	OR	ON	2005/10/17 09:28
S46	9	("4396936"   "5014904"   "5172301"   "5646826"   "5661902"   "5790379"   "6115255"   "6156980"   "6349033").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 09:28
S47	6	(case or shell) with (opening or via or hole) with inject\$3 and "circuit card"	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 09:53
S48	2357	(case or shell) with (opening or via or hole) with inject\$3 and thermal	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 09:54
S49	5	(case or shell) with (opening or via or hole) with (thermal near4 filler)	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 10:04
S50	4858	silver near3 (silicone or epoxy)	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 10:05
S51	232	silver near3 (silicone or epoxy) with thermal	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 10:05

S52	5	silver near3 (silicone or epoxy) with thermal and S36	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 10:27
S53	626	composite with "carbon fiber" with (case or shell or enclosure or cover or outside)	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 10:29
S54	1	S36 and S53	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 10:29
S55	9	S28 and S53	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 10:29
S56	1	10/705906	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 11:51
S57	0	S56 and "217"	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 11:51
S58	2	(("5208732") or ("5541448")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/17 13:09